Standardized Information for Process/Product Change Notification (PCN)

		1. PCN ba	asic data			
1.1 Company	TAIWAN SEMICONDUCTOR					
1.2 PCN No.		PCN16028				
1.3 Title of Po	CN	Change of wafer supplier				
1.4 Product 0	Category	Active Components - Discrete Components		•		
1.5 Issue dat	е	2016/11/21				
1.6 PCN revision history (optional)		1.7 Issue date of previous revision (optional)	1.8 Delta to previous revision (optional)			

2. PCN Team							
2.1 Contact supplier	2.1 Contact supplier						
2.1.1 Name	Sunnie Pan						
2.1.2 Phone	+886-2-8913-1588 Ext:2205						
2.1.3 Email	sunnie@mil.ts.com.tw						
2.2 Team supplier (optional)							
2.2.1 Name (optional)	2.2.2 Phone (optional)	2.2.3 Email (optional)					
Celia Huang	886-2-8913-1588 Ext.2125	celia@mail.ts.com.tw					
Jing Li	86-002-59816699 Ext.3032	Lijing@mail.tew.com.cn					

	3. Changes						
No.	3.0 Ident	3.2 Type of change					
#1	SEM-PW-11	PROCESS - WAFER PRODUCTION	Change of wafer supplier.				
#2							
#3							
#4							
#5							

	4. Description of change	
	Old	New
Change #1	Supplier A	Supplier B
Change #2	Die size : 0.28*0.28mm	Die size : 0.32*0.32mm
Change #3		
Change #4		
Change #5		
4.6 Anticipated impact on form, fit, function, reliability or processability?	Not impact the form, fit, function, reliability or processa	bility
4.7 Reference parts with customer number (optional)		

5. Reason / motivation for change					
5.1 Motivation Expand production line					
5.2 Additional explanation (optional)					

6. Marking of parts / traceability of change				
6.1 Description	Use date code to control			

7. Timing / schedule					
7.1 Date of qualification results	2016/11/04				
7.2 Last order date (optional)	2017/03/20				
7.3 Last delivery date (optional)	2018/03/20				
7.4 Intended start of delivery	2017/02/21				
7.5 Qualification samples available?	When get customer order	and after 2 weeks can be submitted			
7.6 Customer feedback required until	2016/12/20				

8. Qualification / validation						
8.1 Description According to JESD22						
(e.g. qual. plan/report, AEC-Q)						
8.2 Qualification report and	available (see attachement)	issue date	2016/11/04			
qualification results	available (see attachement)					

	9. Input to customer for risk assessment process
Human Resource : Low Risk	
Equipment : Low Risk	
Technique-Wafer : Low Risk	
Technique-Assembly : Low Risk	
Sample submit time : within 30 days	
Form/ Fit / Function : Low Risk	
Reliability : Low Risk	

10. Attachments (e.g. new	datasheet, additional documenta	tion, pictures, process flow, san	nple plan,)
Please see in the official announcement m	ail.		

11. Affected parts									
11.1 Current				11.2 New (if applicable)					
11.1.1 Customer Part No.	11.1.2 Supplier Part Name	11.1.3 Supplier Part No. (optional)	11.1.4 Package Name	11.1.5 Part Description (optional)	11.1.6 Additional Part Information	11.2.2 Supplier Part Name	11.2.3 Supplier Part No. (optional)	11.2.4 Package Name	11.2.6 Additional Part Information
		(optional)		(optional)	(antional)		(optional)		(antional)
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